



SF305R 无卤聚酰亚胺薄膜补强板

SF305R

Halogen-free type polyimide film based stiffener

特点

- 无卤无磷。
- 粘结强度高，尺寸稳定性好。
- 优秀的耐热性、耐化学性和绝缘性能。
- 溢胶量低，加工性好，适于快速压合和传统压合。
- 满足 RoHS 指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

FEATURES

- Halogen free and phosphorus free.
- High bonding strength, good dimensional stability
- Excellent soldering reliability, chemical resistance and electrical properties.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg,Cd, Cr⁶⁺,PBB,PBDE, etc..

应用领域

挠性印制电路板用补强板。

APPLICATIONS

Stiffener for FPC.

性能表 GENERAL PROPERTIES

性能项目 Test Item	测试方法 Test Method	单位 Unit	标准值* Standard Value	典型值 Typical Value	
				SF305R 5025	SF305R 8025
溢胶量 Resin Flow	Shengyi Method	mm	<0.15	<0.15	<0.15
剥离强度 Peel Strength (90°)	IPC-TM-650,No.2.4.9 Method A Method C	N/mm	≥0.7 ≥0.7	1.2 1.0	1.2 1.1
热应力 Thermal Stress	IPC-TM-650,No.2.4.13	-	Pass	Pass	Pass
尺寸稳定性 Dimensional Stability	Shengyi Method	%	±0.1	±0.08	±0.08
体积电阻率 Volume Resistivity	IPC-TM-650,No.2.5.17	MΩ-cm	≥10 ⁶	2.0×10 ⁶	2.5×10 ⁶
表面电阻 Surface Resistance	IPC-TM-650,No.2.5.17	MΩ	≥10 ⁴	1.5×10 ⁵	1.5×10 ⁵

注释 Explanations: * Certified to IPC-4203/2 Epoxy adhesive on one or two sides of polyimide dielectric and Shengyi standard.



SF305R 无卤聚酰亚胺薄膜补强板

SF305R

Halogen-free type polyimide film

产品规格代码描述 Product Code Description

SF305R 50 25

胶粘剂厚度 Adhesive Thickness: 25 - 25 μ m; 35 - 35 μ m

PI 膜厚度 PI film Thickness: 50 - 125 μ m; 90 - 300 μ m

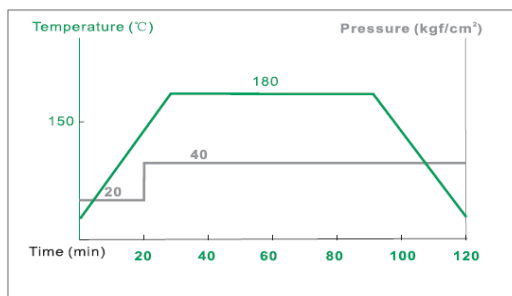
生益无卤补强板产品编号 Shengyi Halogen-free Stiffener Designation

常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

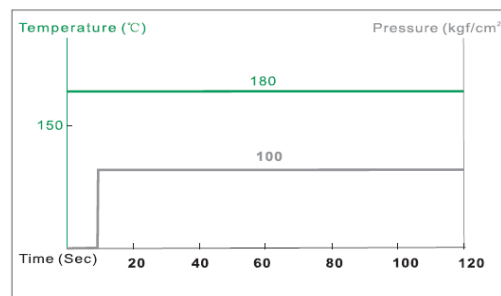
产品规格 Specifications	PI 膜厚度 (μ m) PI film Thickness (μ m)	胶粘剂厚度 (μ m) Adhesive Thickness (μ m)
SF305R 3025	75	25
SF305R 4025	100	25
SF305R 5025	125	25
SF305R 6025	150	25
SF305R 7025	175	25
SF305R 8025	200	25
SF305R 9025	225	25
SF305R A25	250	25
SF305R B25	275	25
SF305R C25	300	25
SF305R 3000	75	00
SF305R 4000	100	00
SF305R 5000	125	00
SF305R 6000	150	00
SF305R 7000	175	00
SF305R 8000	200	00
SF305R 9000	225	00
SF305R A00	250	00
SF305R B00	275	00
SF305R C00	300	00

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE





SF305R 无卤聚酰亚胺薄膜补强板

SF305R Halogen-free type polyimide film

传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件是 160-170℃ 、60-90 分钟。
The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-170℃ for 60-90min.

包装PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm，每卷100+2/-0米或200+2/-0米；其它规格、尺寸可根据客户要求而定。SF305R is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.